

## 1. General description

Hyperfast power diode (Bare die after sawn).

## 2. Features and benefits

- Low Forward Voltage Drop
- Low leakage current
- Fast reverse recovery
- Bare die

## 3. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{RRM}^*$	repetitive peak reverse voltage		-	-	1200	V
$I_{F(AV)}^{**}$	average forward current	$\delta = 0.5$ ; square-wave pulse	-	-	5	A
<b>Static characteristics</b>						
$V_F^{**}$	forward voltage	$I_F = 5\text{ A}$ ; $T_j = 25\text{ °C}$	-	2.4	3.2	V
<b>Dynamic characteristics</b>						
$t_{rr}^{**}$	reverse recovery time	$I_F = 1\text{ A}$ ; $V_R = 30\text{ V}$ ; $di_F/dt = 100\text{ A}/\mu\text{s}$ ; $T_j = 25\text{ °C}$	-	36	-	ns

## 4. Ordering information

Table 2. Ordering information

Type number	Package		
	Name	Description	Version
WNB087C5APPS12	Wafer	Bare die on wafer	Die

## 5. Limiting values

**Table 3. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{RRM}^*$	repetitive peak reverse voltage		-	1200	V
$V_{RWM}^*$	crest working reverse voltage		-	1200	V
$V_R^*$	reverse voltage	DC	-	1200	V
$I_{F(AV)}^{**}$	average forward current	$\delta = 0.5$ ; square-wave pulse	-	5	A
$I_{FRM}^{**}$	repetitive peak forward current	$\delta = 0.5$ ; $t_p = 25 \mu\text{s}$ ; square-wave pulse	-	10	A
$I_{FSM}^{**}$	non-repetitive peak forward current	$t_p = 10 \text{ ms}$ ; $T_{j(\text{init})} = 25 \text{ }^\circ\text{C}$ ; sine-wave pulse	-	55	A
		$t_p = 8.3 \text{ ms}$ ; $T_{j(\text{init})} = 25 \text{ }^\circ\text{C}$ ; sine-wave pulse	-	60	A
$T_{\text{stg}}^{**}$	storage temperature		-65	175	$^\circ\text{C}$
$T_j^{**}$	junction temperature			175	$^\circ\text{C}$

## 6. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_F^*$	forward voltage	$I_F = 5\text{ A}; T_J = 25\text{ °C}$	-	2.4	3.2	V
$V_F^{**}$	forward voltage	$I_F = 5\text{ A}; T_J = 150\text{ °C}$	-	2	-	V
$I_R^*$	reverse current	$V_R = 1200\text{ V}; T_J = 25\text{ °C}$	-	-	100	$\mu\text{A}$
$I_R^{**}$	reverse current	$V_R = 1200\text{ V}; T_J = 150\text{ °C}$	-	-	500	$\mu\text{A}$
<b>Dynamic characteristics</b>						
$t_{rr}^{**}$	reverse recovery time	$I_F = 1\text{ A}; V_R = 30\text{ V}; di_F/dt = 100\text{ A}/\mu\text{s}; T_J = 25\text{ °C}$	-	36	-	ns
		$I_F = 5\text{ A}; V_R = 400\text{ V}; di_F/dt = 500\text{ A}/\mu\text{s}; T_J = 25\text{ °C}$	-	42	-	ns
		$I_F = 5\text{ A}; V_R = 400\text{ V}; di_F/dt = 500\text{ A}/\mu\text{s}; T_J = 125\text{ °C}$	-	63	-	ns
		$I_F = 5\text{ A}; V_R = 400\text{ V}; di_F/dt = 500\text{ A}/\mu\text{s}; T_J = 150\text{ °C}$	-	72	-	ns

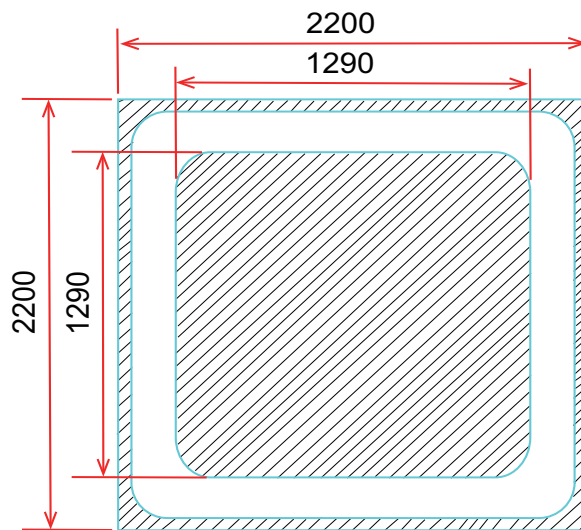
Notes:

(1) \* mean that parameter are 100% test at  $T_{amb} = 25\text{ °C}$

(2) \*\* means that the guaranteed ratings and parameter limits will depend on the assembled structure. When correctly assembled with suitable die bonding and wire bonding, the device will have ratings and characteristics guaranteed in this data sheet, similar to the assembled devices BYC5-1200P.

MECHANICAL PATAMETER		
Chip size	2.2 x 2.2	mm <sup>2</sup>
Anode pad size	1.29 x 1.29	mm <sup>2</sup>
Area total / active	4.84 / 1.66	mm <sup>2</sup>
Thickness	300	μm
Wafer size	125	mm
Max possible chips per wafer	2229	pcs
Passivation	P.E.C.V.D./ Planar	
Front metal	Al	
Back metal	Ti Ni Ag	

**CHIP LAYOUT**



**Die size: 2200μm x 2200μm**  
**Bond pad size: 1290μm x 1290μm**

## 7. Legal information

### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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Date of release: 13 December 2018

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